

Patent  
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**IN THE CLAIMS**

1. (Previously Presented) A heat transfer device for intravascular temperature control of a patient, comprising:

a flexible layer of a substantially conductive material, the flexible layer having in part the shape of a helical groove, and shaped and configured such that the flexible layer lacks an undercut and may be removed from a multi-part mold,

wherein the heat transfer device includes at least two heat transfer segments separated by an articulating joint, wherein each heat transfer segment has a flexible layer.

2. (Original) The device of claim 1, wherein the flexible layer is formed of a metal selected from the group consisting essentially of Fe, Ti, Ta, nitinol, stainless steel, Al, Ag, Au, Cu, and Ni.

3. (Previously Presented) The device of claim 1, wherein a total outside diameter of the device is between about 9 f to 18 f.

4. (Canceled)

5. (Previously Presented) The device of claim 1, wherein the articulating joints are shaped and configured as bellows.

6. (Previously Presented) The device of claim 1, wherein the articulating joints are shaped and configured as flexible tubes.

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7. (Original) The device of claim 1, wherein the flexible layer has a thermal conductivity in the range of about 0.1 to 4 W/cm-K.

8. (Previously Presented) The device of claim 1, each segment has at least two helical grooves, one of said at least two helical grooves having opposite helicity from the at least two helical grooves on another of said helical grooves.

9. (Original) The device of claim 8, wherein the two helical grooves on each segment are joined by a circumferential segment.

10-13. (Canceled)